

Virtual **MLCAD** 2020 Call for Papers

**2nd ACM/IEEE Workshop on Machine Learning for CAD,
16-20 November, 2020**

MLCAD Workshop

This workshop focuses on Machine Learning (ML) methods for all aspects of CAD and electronic system design. The workshop is sponsored by both the ACM Special Interest Group on Design Automation (SIGDA) and the IEEE Council on Electronic Design Automation (CEDA). The workshop program will, in addition to technical presentations, also have keynote and invited speakers from major CAD and industrial companies who will present their vision on machine learning for CAD. The workshop will be held virtually this year.

Paper Submission

Submissions should be full-length papers of up to six pages (PDF format, double-column, US letter size, using the ACM Conference format). Submissions must be anonymous (i.e., double-blind review process). Submissions exceeding 6 pages will be rejected. Submitted papers must describe original work that has not been published/accepted or is currently under review by another journal, conference, symposium, or workshop. We encourage senior researchers as well as Ph.D. students to be part of this workshop.

Workshop Proceedings

Formal shared ACM/IEEE proceedings will be published containing all accepted papers. Accepted papers will be available in both IEEE Xplore Digital Library and the ACM Digital Library.

IEEE Design & Test Magazine Special Issue

A Special Issue on MLCAD 2020 is planned in the IEEE Design & Test Magazine. Authors of accepted papers will be eligible to submit an extended version of their work to the special issue of this high-impact magazine.

Venue MLCAD 2020 will be held virtually this year from 16-20 November due to COVID-19. Please check the MLCAD website for further details: <http://mlcad.itec.kit.edu/>

Exemplary topics of interest:

1. ML for system-level design
2. ML approaches to logic design
3. ML for physical design
4. ML for analog design
5. ML for power and thermal management
6. ML for Design Technology Co-Optimization (DTCO)
7. ML methods to predict aging and reliability
8. Labeled and unlabeled data in ML for CAD
9. ML techniques for resource management in many cores
10. ML for Verification and Validation

Paper Submission:

August 07, 2020

Author Notification:

October 07, 2020

Camera-ready Version:

October 30, 2020

Registration Deadline:

October 30, 2020

Workshop (Virtual):

November 16-20, 2020

Website:

<http://mlcad.itec.kit.edu/>

General Chairs

Ulf Schlichtmann, Technical University of Munich
Raviv Gal, IBM Research, Haifa

Program Chairs

Hussam Amrouch, University of Stuttgart
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